

PATENT NO.: 47618
 41536
 4856189(U.S.A.)



FEATURES

- End stackable for standard 0.1" integrated circuit pitch.
- Molded 0.3" integrated circuit packing outline allowing automatic insertion.
- Smaller size makes better heat convection during PC board reflow wave soldering.
- Top tape sealed to withstand wave soldering, board washing.
- All plastics are UL 94V-0 grade fire retardant.
- Twin contacts designed to ensure stable contact.
- Gold plated contact to ensure low contact resistance and Tin plated terminals to prevent contamination during soldering.

SPECIFICATIONS

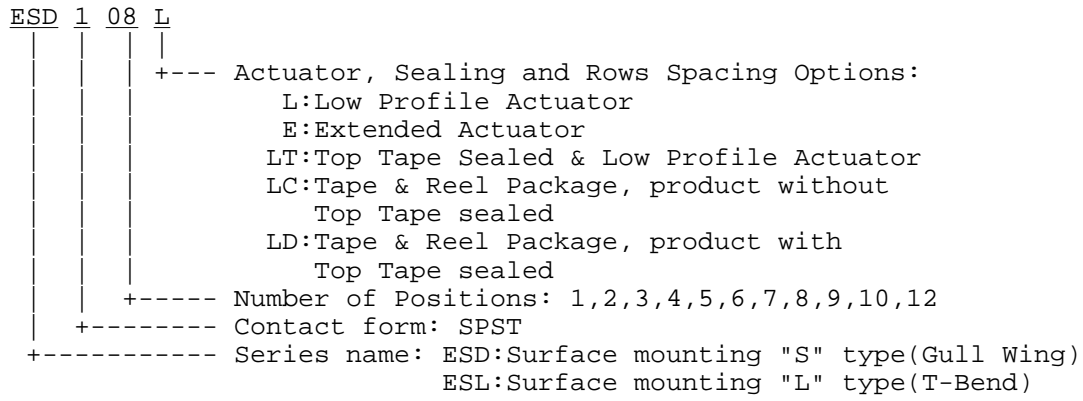
1. ELECTRICAL

Contact rating	
switching	25 mA, 24 VDC
non-switching	100 mA, 50 VDC
Contact resistance	
initial	50 mΩ Max.
after life test	100 mΩ Max.
Insulation resistance	1000 MΩ Min. at 100 VDC
Dielectric strength	500 VDC Min. for 60 seconds
Capacitance between adjacent switches	5 pF Max.

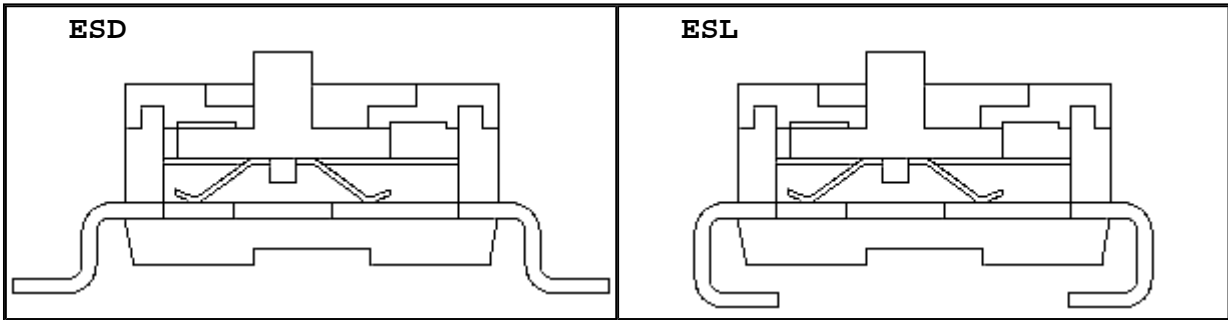
2. MECHANICAL

Temperature rating	
operating	-25°C to +70°C
storage	-40°C to +85°C
Operation force	800g Max.
Mechanical life	2000 operations
Humidity	95%RH, 40°C for 96 Hrs.
Vibration	Per MIL-STD-202F, method 204D
Solderability	after flux 230±5°C for 5±0.5 seconds, 95% coverage
Resistance to soldering Heat	260±5°C for 5°C seconds.
Reflow soldering heat for SMT type (reference only)	reflow zone 230±5°C for 30 seconds

PART NUMBERING SYSTEM



CONSTRUCTION

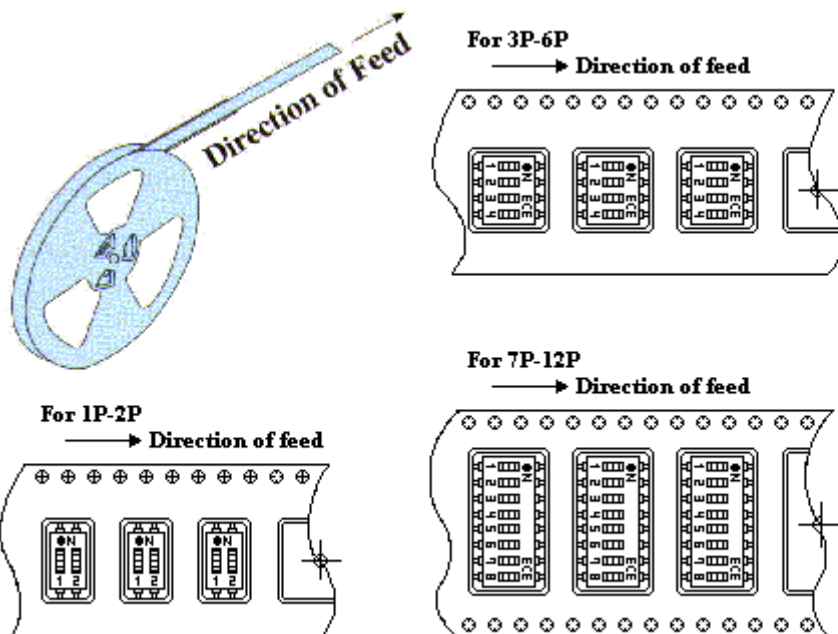


OPTIONS

- 1.Special marking and case color available
- 2.Extended Actuator
- 3.Top Tape Sealed



- 4.Tape & Reel Packaging (per EIA STANDARD)



Pole	No. of pcs per reel
1P	2000
2P	1300
3P	1000
4P	1000
5P	1000
6P	1000
7P	1000
8P	1000
10P	1000
12P	1000

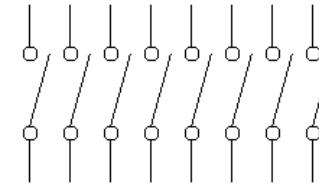
Dimension A

ESD/ESL

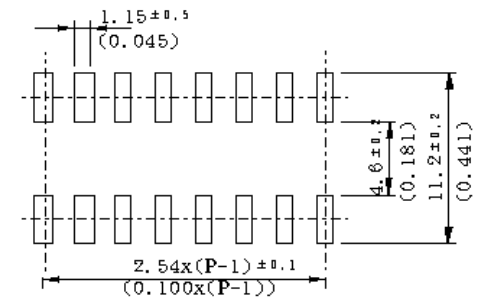
Positions	1	2	3	4	5	6	7	8	9	10	12
A	2.5 (0.098)	5.04 (0.198)	7.58 (0.298)	10.12 (0.398)	12.66 (0.498)	15.20 (0.598)	17.74 (0.698)	20.28 (0.798)	22.82 (0.898)	25.36 (0.998)	30.43 (1.198)

Unit:mm(inch)

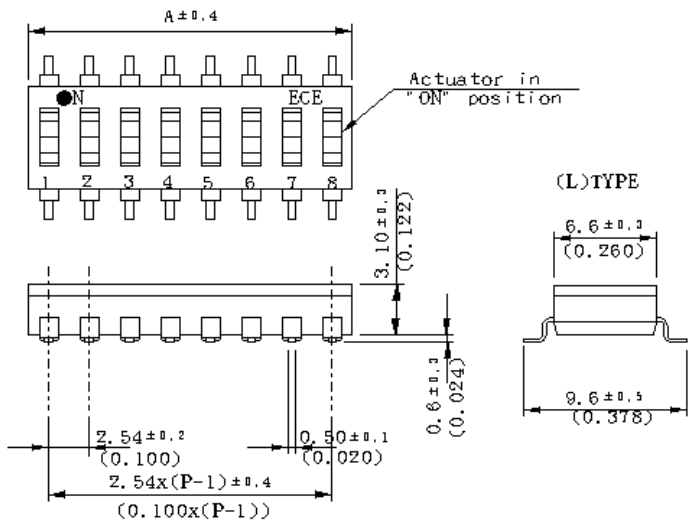
CIRCUIT DIAGRAM



P.C.B PATTERN (TOP VIEW)



ESD



ESL

